

info@atrinelec.com



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Dual Audio Operational Amplifier

General Description

The LM833 is a dual general purpose operational amplifier designed with particular emphasis on performance in audio systems.

This dual amplifier IC utilizes new circuit and processing techniques to deliver low noise, high speed and wide bandwidth without increasing external components or decreasing stability. The LM833 is internally compensated for all closed loop gains and is therefore optimized for all preamp and high level stages in PCM and HiFi systems.

The LM833 is pin-for-pin compatible with industry standard dual operational amplifiers.

Features

Wide dynamic range: >140dB

•	Low input noise voltage:	4.5nV/√ H z
	High slew rate:	7 V/µs (typ); 5V/µs (min)
	High gain bandwidth:	15MHz (typ); 10MHz (min)
	Wide power bandwidth:	120KHz
	Low distortion:	0.002%
	Low offset voltage:	0.3mV
	Large phase margin:	60°

 Available in 8 pin MSOP package

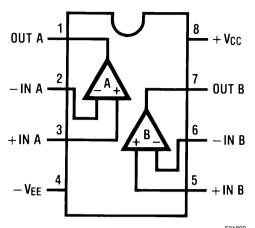
+ VCC -360 2(6) 3(5) -IN+ IN 15 oF 97 1(7) DUT 27 4.7k **\$**4.7k 7.5k 150 50 35 pF 4 — Vee 521801

Schematic Diagram

(1/2 LM833)



Connection Diagram



Order Number LM833M, LM833MX, LM833AM, LM833AMX, LM833N, LM833MM or LM833MMX See NS Package Number M08A, N08E or MUA08A

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

Supply Voltage V _{CC} -V _{EE}	36V
Differential Input Voltage (Note 3) V ₁	±30V
Input Voltage Range (Note 3) VIC	±15V
Power Dissipation (<i>Note 4</i>) P _D	500 mW
Operating Temperature Range T _{OPR}	-40 ~ 85°C
Storage Temperature Range T _{STG}	–60 ~ 150°C
Soldering Information Dual-In-Line Package Soldering (10 seconds)	260°C
Small Outline Package (SOIC and MSOP)	
Vapor Phase (60 seconds)	215°C
Infrared (15 seconds)	220°C
ESD tolerance (<i>Note 5</i>)	1600V

DC Electrical Characteristics (Note 1, Note 2)

 $(T_A = 25^{\circ}C, V_S = \pm 15V)$

Symbol	Parameter	Conditions	Min	Тур	Max	Units
V _{OS}	Input Offset Voltage	R _s = 10Ω		0.3	5	mV
I _{OS}	Input Offset Current			10	200	nA
I _B	Input Bias Current			500	1000	nA
A _V	Voltage Gain	$R_L = 2 k\Omega, V_O = \pm 10V$	90	110		dB
V	Output Voltage Swing	$R_L = 10 \text{ k}\Omega$	±12	±13.5		V
V _{OM}		$R_L = 2 k\Omega$	±12	±13.4		V
V _{CM}	Input Common-Mode Range		±12	±14.0		V
CMRR	Common-Mode Rejection Ratio	$V_{IN} = \pm 12V$	80	100		dB
PSRR	Power Supply Rejection Ratio	V _S = 15 ~ 5V, -15 ~ -5V	80	100		dB
Ι _Q	Supply Current	V _O = 0V, Both Amps		5	8	mA

AC Electrical Characteristics

 $(T_A = 25^{\circ}C, V_S = \pm 15V, R_L = 2 \text{ k}\Omega)$

Symbol	Parameter	Conditions	Min	Тур	Max	Units
SR	Slew Rate	$R_L = 2 k\Omega$	5	7		V/µs
GBW	Gain Bandwidth Product	f = 100 kHz	10	15		MHz
V _{NI}	Equivalent Input Noise Voltage (LM833AM, LM833AMX)	RIAA, R _S = 2.2 kΩ (<i>Note 6</i>)			1.4	μV

Design Electrical Characteristics

 $(T_A = 25^{\circ}C, V_S = \pm 15V)$

The following parameters are not tested or guaranteed.

Symbol	Parameter	Conditions	Тур	Units
$\Delta V_{OS} / \Delta T$	Average Temperature Coefficient		2	µV/°C
	of Input Offset Voltage			
THD	Distortion	R _L = 2 kΩ, f = 20~20 kHz	0.002	%
		$V_{OUT} = 3 \text{ Vrms}, A_V = 1$		
e _n	Input Referred Noise Voltage	R_{S} = 100 Ω , f = 1 kHz	4.5	nV/√Hz



Symbol	Parameter	Conditions	Тур	Units
i _n	Input Referred Noise Current	f = 1 kHz	0.7	pA/√Hz
PBW	Power Bandwidth	$V_{O} = 27 V_{pp}, R_{L} = 2 k\Omega, THD \le 1\%$	120	kHz
f _U	Unity Gain Frequency	Open Loop	9	MHz
φ _M	Phase Margin	Open Loop	60	deg
	Input Referred Cross Talk	f = 20~20 kHz	-120	dB



Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given, however, the typical value is a good indication of device performance.

Note 2: All voltages are measured with respect to the ground pin, unless otherwise specified.

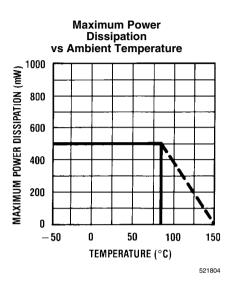
Note 3: If supply voltage is less than $\pm 15V$, it is equal to supply voltage.

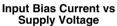
Note 4: This is the permissible value at $T_A \leq 85^{\circ}C$.

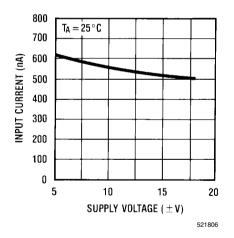
Note 5: Human body model, 1.5 k Ω in series with 100 pF.

Note 6: RIAA Noise Voltage Measurement Circuit

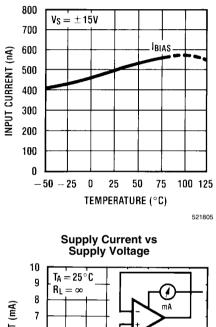
Typical Performance Characteristics

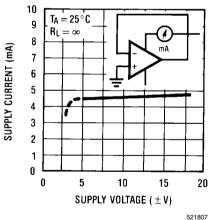




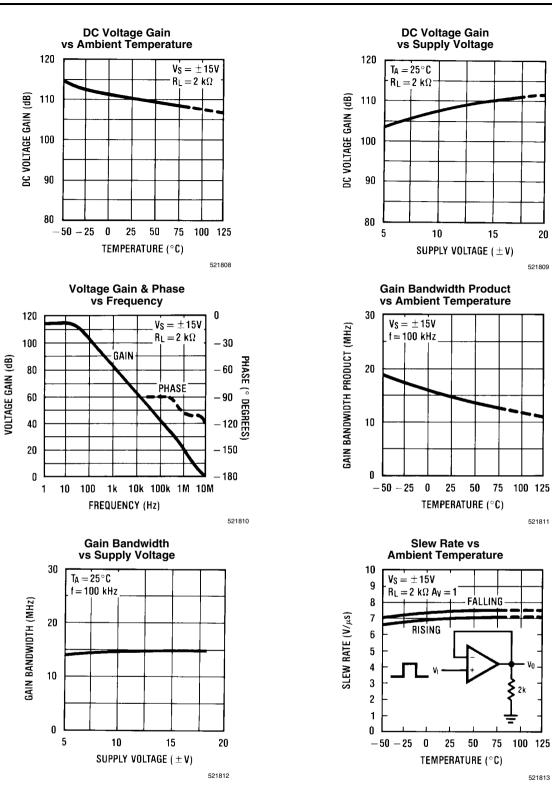


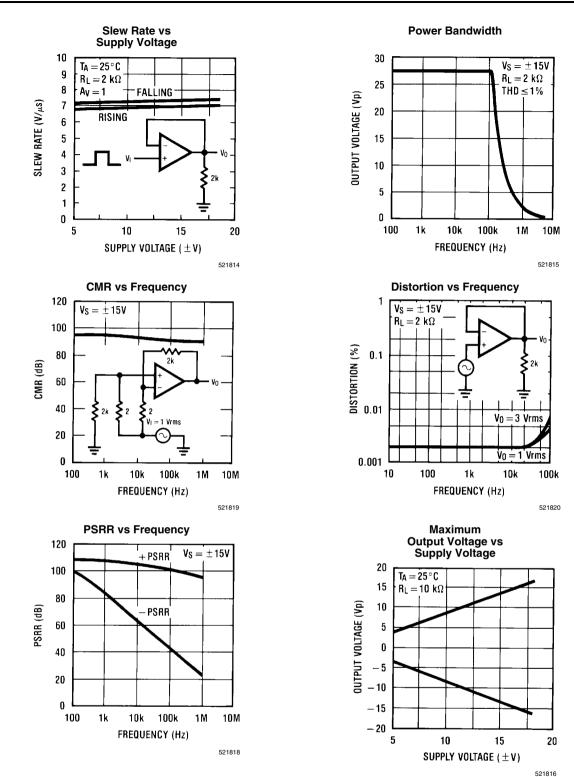
Input Bias Current vs Ambient Temperature



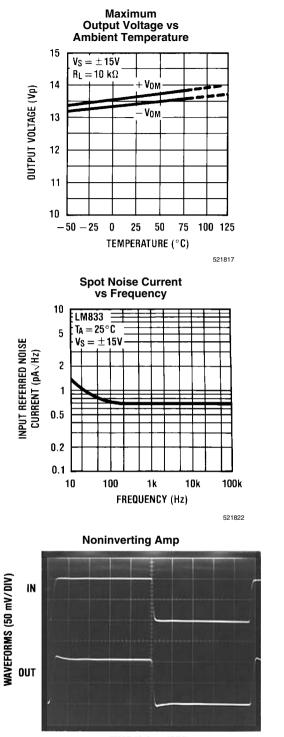








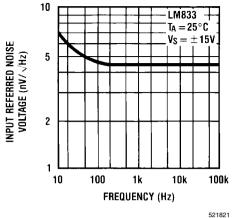




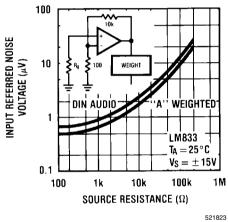
TIME (0.2 µs/DIV)

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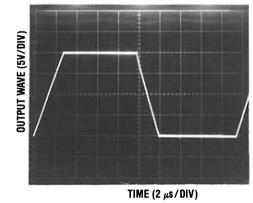
Spot Noise Voltage vs Frequency



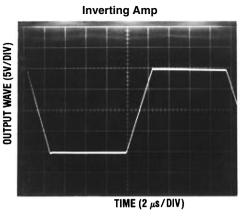
Input Referred Noise Voltage vs Source Resistance



Noninverting Amp



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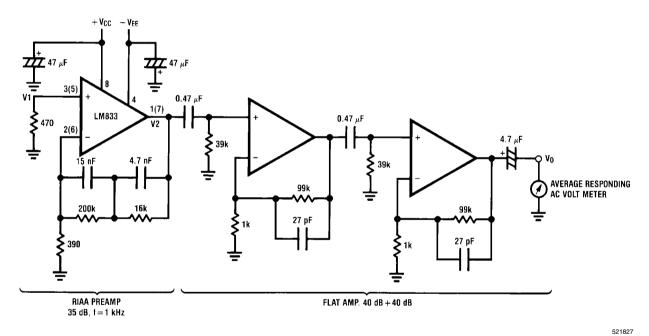
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Application Hints

The LM833 is a high speed op amp with excellent phase margin and stability. Capacitive loads up to 50 pF will cause little change in the phase characteristics of the amplifiers and are therefore allowable.

Capacitive loads greater than 50 pF must be isolated from the output. The most straightforward way to do this is to put a resistor in series with the output. This resistor will also prevent excess power dissipation if the output is accidentally shorted.

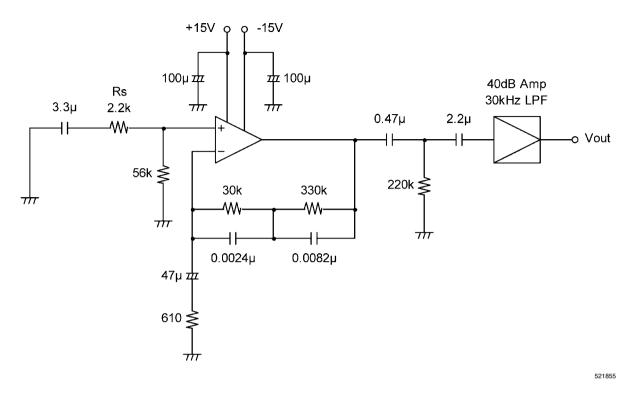
Noise Measurement Circuit

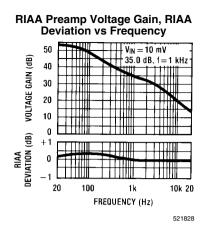


Complete shielding is required to prevent induced pick up from external sources. Always check with oscilloscope for power line noise.

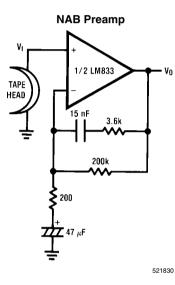
Total Gain: 115 dB @f = 1 kHz Input Referred Noise Voltage: e_n = V0/560,000 (V)

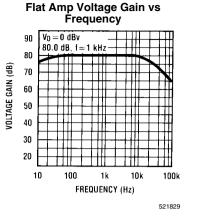
RIAA Noise Voltage Measurement Circuit

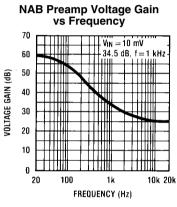




Typical Applications



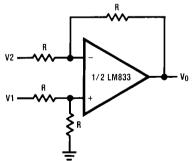




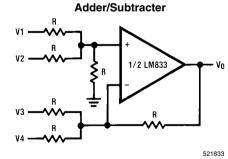
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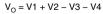






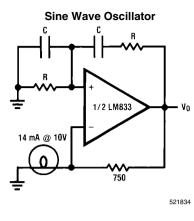
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 $V_0 = V1 - V2$







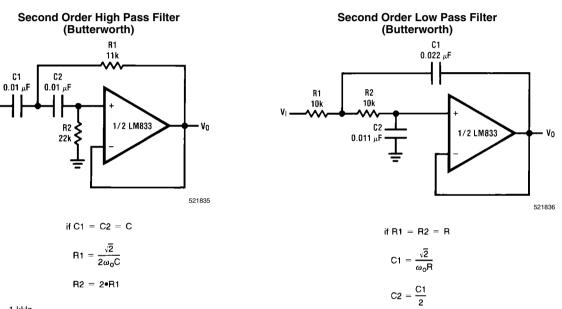


Illustration is $f_0 = 1 \text{ kHz}$

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Illustration is $f_0 = 1 \text{ kHz}$

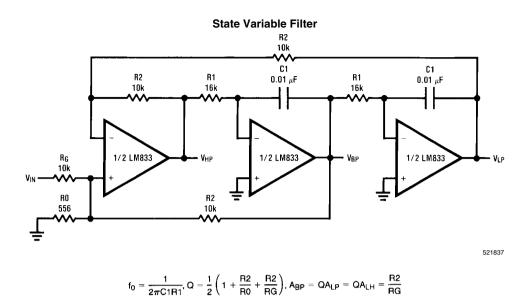
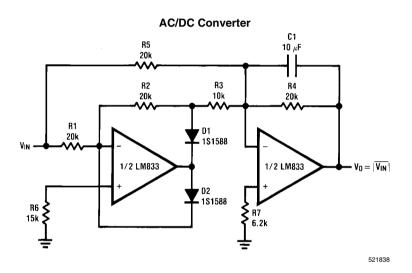
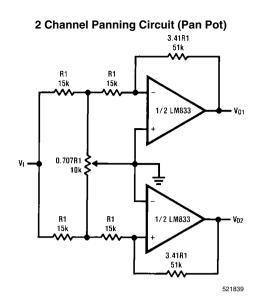
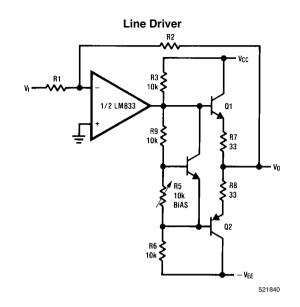


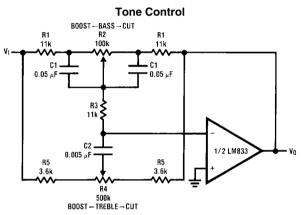
Illustration is $f_0 = 1 \text{ kHz}$, Q = 10, $A_{BP} = 1$











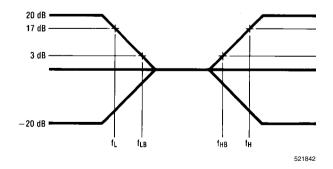
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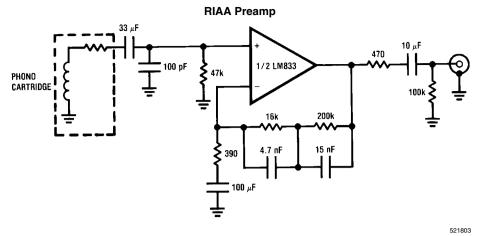
$$f_{L} = \frac{1}{2\pi R2C1}, f_{LB} = \frac{1}{2\pi R1C1}$$
$$f_{H} = \frac{1}{2\pi R5C2}, f_{HB} = \frac{1}{2\pi (R1 + R5 + 2R3)C2}$$

Illustration is:

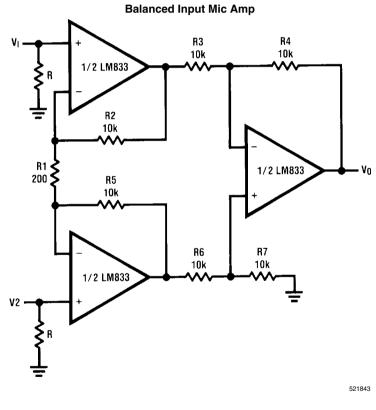
 $\mathrm{f_L}=32~\mathrm{Hz},~\mathrm{f_{LB}}=320~\mathrm{Hz}$

 $f_H = 11 \text{ kHz}, f_{HB} = 1.1 \text{ kHz}$





 $\begin{array}{l} A_v = 35 \text{ dB} \\ E_n = 0.33 \ \mu\text{V} \\ \text{S/N} = 90 \ \text{dB} \\ \text{f} = 1 \ \text{kHz} \\ \text{A Weighted} \\ \text{A Weighted}, \ \text{V}_{\text{IN}} = 10 \ \text{mV} \\ @\text{f} = 1 \ \text{kHz} \end{array}$

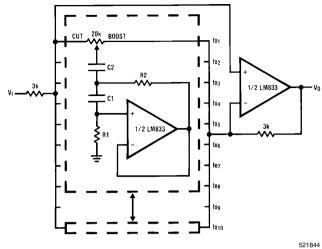


If R2 = R5, R3 = R6, R4 = R7 V0 = $\left(1 + \frac{2R2}{R1}\right)\frac{R4}{R3}(V2 - V1)$

Illustration is: V0 = 101(V2 - V1)



10 Band Graphic Equalizer



fo (Hz)	C ₁	C ₂	R ₁	R ₂
32	0.12µF	4.7µF	75kΩ	500Ω
64	0.056µF	3.3µF	68kΩ	510Ω
125	0.033µF	1.5µF	62kΩ	510Ω
250	0.015µF	0.82µF	68kΩ	470Ω
500	8200pF	0.39µF	62kΩ	470Ω
1k	3900pF	0.22µF	68kΩ	470Ω
2k	2000pF	0.1µF	68kΩ	470Ω
4k	1100pF	0.056µF	62kΩ	470Ω
8k	510pF	0.022µF	68kΩ	510Ω
16k	330pF	0.012µF	51kΩ	510Ω

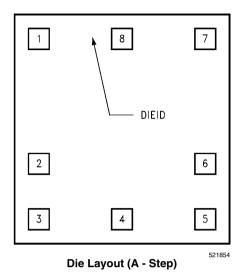
Note 7: At volume of change = $\pm 12 \text{ dB}$

Q = 1.7

Reference: "AUDIO/RADIO HANDBOOK", National Semiconductor, 1980, Page 2–61



LM833 MDC MWC DUAL AUDIO OPERATIONAL AMPLIFIER



Die/Wafer Characteristics

Fabrication Attributes		General Die Information		
Physical Die Identification	LM833A	Bond Pad Opening Size (min)	110µm x 110µm	
Die Step	A	Bond Pad Metalization	ALUMINUM	
Physical Attributes		Passivation	VOM NITRIDE	
Wafer Diameter	150mm	Back Side Metal	BARE BACK	
Dise Size (Drawn)	1219µm x 1270µm 48mils x 50mils	Back Side Connection	Floating	
Thickness	406µm Nominal		•	
Min Pitch	288µm Nominal			

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

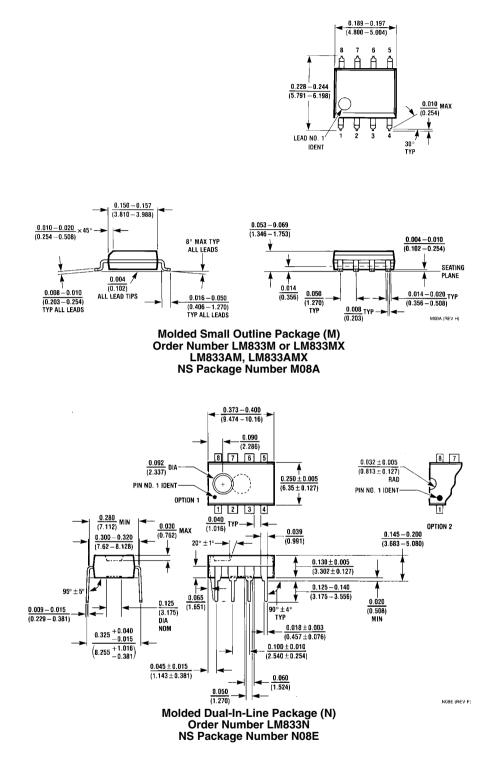
Die Bond Pad Coordinate Locations (A - Step)						
	(Referen	ced to die center,	coordinates in μn	n) NC = No Conne	ction	
SIGNAL NAME		X/Y COO	RDINATES	PAD SIZE		
SIGNAL NAME	PAD NUMBER	X	Y	X		Y
OUTPUT A	1	-476	500	110	x	110
INPUT A-	2	-476	-212	110	x	110
INPUT A+	3	-476	-500	110	x	110
VEE-	4	-0	-500	110	x	110
INPUT B+	5	476	-500	110	x	110
INPUT B-	6	476	-212	110	x	110
OUTPUT B	7	476	500	110	x	110
VCC+	8	0	500	110	x	110



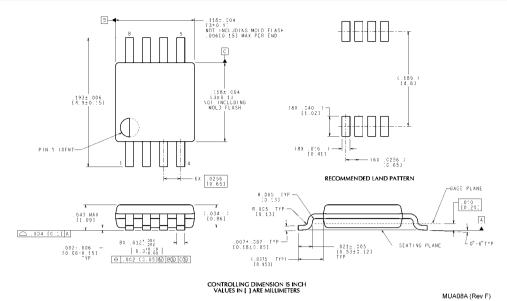
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Tel #:	1 877 Dial Die 1 877 342 5343	
Fax:	1 207 541 6140	
IN EUROPE		
Tel:	49 (0) 8141 351492 / 1495	
Fax:	49 (0) 8141 351470	
IN ASIA PACIFIC		
Tel:	(852) 27371701	
IN JAPAN		
Tel:	81 043 299 2308	

TEXAS INSTRUMENTS

Physical Dimensions inches (millimeters) unless otherwise noted







8-Lead (0.118" Wide) Molded Mini Small Outline Package Order Number LM833MM or LM833MMX NS Package Number MUA08A



Notes

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